

N-Channel JFET 40 V, 55 to 95 μA, 0.10 ms, CP **2SK545**

\$6. 50 / CP3

CASE 318BJ

MARKING DIAGRAM



B11 = Specific Device Code

Features

- Small IGSS
- Small C_{iss}
- Ultrasmall Package permitting 2SK545-applied Sets to be Compact
- This is a Pb–Free Device

Applications

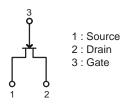
- Impedance Converter Applications
- Infrared Sensor

ABSOLUTE MAXIMUM RATINGS (at $T_A = 25$ °C)

| Parameter | Symbol | Ratings | Unit |
|-----------------------------|------------------|-------------|------|
| Drain-to-Source Voltage | V _{DSS} | 40 | V |
| Gate-to-Drain Voltage | V_{GDS} | -40 | V |
| Gate Current | I _G | 10 | mA |
| Drain Current | I _D | 1 | mA |
| Allowable Power Dissipation | P_{D} | 100 | mW |
| Junction Temperature | TJ | 125 | °C |
| Storage Temperature | T _{STG} | -55 to +125 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ELECTRICAL CONNECTION



ORDERING INFORMATION

| Device | Package | Shipping [†] |
|---------------------|------------------------|-----------------------|
| 2SK545-11D- TB-E | SC-59/CP3 (Pb-Free) | 3000 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Table 1. ELECTRICAL CHARACTERISTICS (at T_A = 25°C)

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|---------------------------------|----------------------|--|------|------|------|------|
| Gate-to-Drain Breakdown Voltage | V _{(BR)GDS} | $I_D = -10 \mu A, V_{DS} = 0 V$ | -40 | | | V |
| Gate Cutoff Current | I _{GSS} | $V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$ | | | -500 | pА |
| Drain Current | I _{DSS} | V _{DS} = 10 V, V _{GS} = 0 V | 55 | | 95 | μΑ |
| Cutoff Voltage | V _{GS(off)} | $V_{DS} = 10 \text{ V}, I_D = 1 \mu A$ | | -1.2 | -4.0 | V |
| Forward Transfer Admittance | yfs | $V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ kHz}$ | 0.05 | 0.10 | | ms |
| Input Capacitance | C _{iss} | V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz | | 1.7 | | pF |
| Reverse Transfer Capacitance | C _{rss} | V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz | | 0.7 | | pF |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

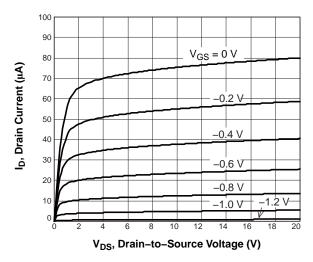


Figure 1. Drain Current vs. Drain-to-Source Voltage

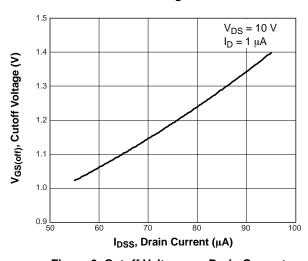


Figure 3. Cutoff Voltage vs. Drain Current

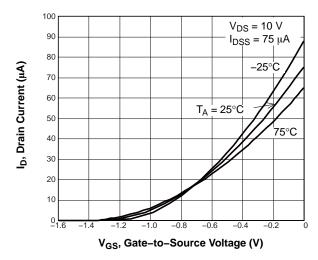


Figure 2. Drain Current vs. Gate-to-Source Voltage

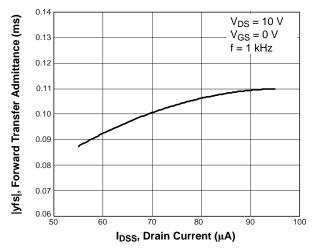


Figure 4. Forward Transfer Admittance vs. Drain Current

2SK545

TYPICAL CHARACTERISTICS

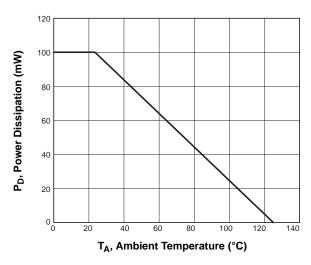


Figure 5. Power Dissipation vs. Ambient Temperature

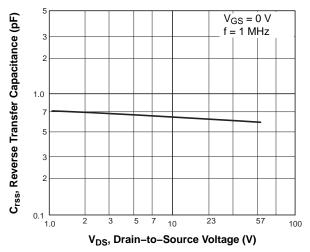


Figure 7. Reverse Transfer Capacitance vs. Drain-to-Source Voltage

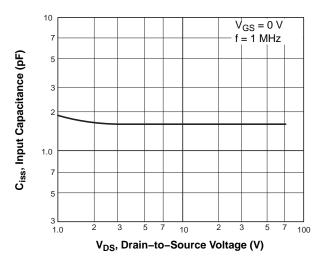


Figure 6. Input Capacitance vs. Drain-to-Source Voltage







E1

е

TOP VIEW

SIDE VIEW

SC-59 / CP3 CASE 318BJ ISSUE O

DATE 09 JAN 2015



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

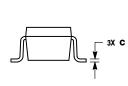
 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER SIDE.

 4. DIMENSIONS D AND E1 ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.

 5. DIMENSIONS D AND CA ADDLY TO THE ELAT SECTION OF THE
- DIMENSIONS 6 AND 6 APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.20 FROM THE TIP.

| | MILLIMETERS | | |
|-----|-------------|------|--|
| DIM | MIN | MAX | |
| Α | 0.95 | 1.35 | |
| A1 | 0.00 | 0.10 | |
| A2 | 0.20 | 0.40 | |
| b | 0.35 | 0.50 | |
| С | 0.10 | 0.20 | |
| D | 2.75 | 3.05 | |
| E | 2.30 | 2.70 | |
| E1 | 1.35 | 1.65 | |
| е | 0.95 BSC | | |
| L | 0.35 | 0.75 | |



END VIEW

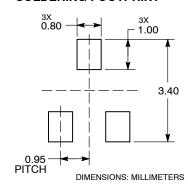
RECOMMENDED SOLDERING FOOTPRINT*

3X L

зх b

⊕ 0.10 M C A

C SEATING PLANE



^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM



= Specific Device Code XXX = Date Code Μ

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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